BONDING + SEALING + ENCAPSULATION



TECHNICAL DATASHEET

1650

(Resin 1649 + Hardener 1600)

Description

1650 is a pasty, slow curing two-component grade, which is based on modified methyl methacrylate. The product bonds various plastics and metals as well as combinations of both of them. Dependent on ambient temperature, the 10:1 (by volume) mixed adhesive shows an open time of approximately 20 minutes, fixture time of 45 minutes (at 23°C).

1650 is mainly used as an universal grade for industrial applications:

Household appliance (white ware), advertising panels, traffic guidance systems, electronic and electrical engineering, vehicle industry, furnishment, windows and doors, bus-, truck-, rail- and car industry, boat and ship construction.

Advantages

- Good adhesion to a wide range of materials
- Non-dropping paste
- Overbridges gaps up to 2mm
- Excellent resistance against dynamic loads
- · Resistant against outside conditions and humidity
- 100% reactive compound

Product data

Chemical base Curing system Mixing ratio Methyl methacrylate adhesive 2-Component-System 10:1 (resin: hardener by volume)

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Physical properties (uncured)

Viscosity	Resin	1649	~130'000 mPa•s
	Hardener	1600	~55'000 mPa•s
Density	Resin	1649	1.00 g/cm ³
	Hardener	1600	1.12 – 1.15 g/cm ³

Colour	Resin	1649	Beige
	Hardener	1600	White

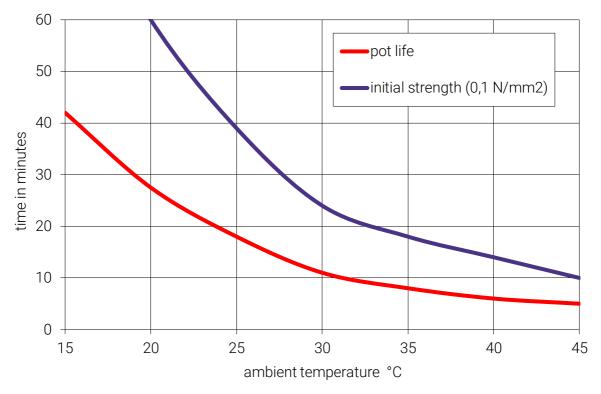
Gap filling Up to 2 mm

Curing properties

 $\begin{array}{ll} \text{Open time} & \sim 20 \text{ minutes} \\ \text{Fixture time } [\sim 0.1 \text{ N/mm}^2] & \sim 45 \text{ minutes} \\ \text{Final strength} & \sim 24 \text{ hours} \end{array}$

Application temperature +10 °C to +40 °C

Curing behaviour



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Physical properties (cured):

Usage temperature - 40°C to + 100°C

Glass transition temperature (DIN 53445) ~ 86°C

Shore D-hardness (DIN 53505) ~ 70

Tensile strength (DIN 53504) ~ 15 N/mm²

after 24 h at 23°C

Elongation at break ~ 30 %

after 24 h at 23°C

Lap shear strength (DIN EN 1465)

after 24 h at 23°C

 $\begin{array}{lll} \text{Steel} & \sim 21 \text{ N/mm}^2 \\ \text{Stainless Steel} & \sim 20 \text{ N/mm}^2 \\ \text{Aluminium} & \sim 20 \text{ N/mm}^2 \end{array}$

GFRP (X)
ABS (X)
PMMA (X)

(X) = Failure of test specimen

Handling and storage

Due to the high reactivity of the product and the exothermic curing process, never mix bigger amount of the components. The heat might evaporate parts of the formulation and cause strong smell. Do not waste exceeded material in plastic containers, because of the danger of melting.

Slight serum formation may occur during storage.

The serum does not imply any quality issues and can be ejected when levelling the cartridge before first use.

Precautions

For your own safety, please refer to the information of the concerned MSDS and for the correct handling the "user instructions".

The information in this data sheet is based on the results of our research and experience. However, the suggestions herein concerning the use, application, and processing of the products (collectively, "the methods") are non-binding recommendations only. It is the user's sole responsibility to determine the suitability and safety of these methods, based on the user's particular purpose in using the products. Before relying on the reliability and safety of any parts that are bonded using the products, it is extremely important that the user test the reliability and safety of the parts that are bonded. Failure to do so could result in serious personal injury. Because of the use of the products are within the purchaser's sole control, Kisling Corporation specifically disclaims all warranties, express or implied, including warranties of merchantability or fitness for a particular purpose, arising from the sale or use of the products described herein. Kisling Corporation specifically disclaims any liability for consequential, incidental, or other damages of any kind, including lost profits. Kisling Corporation's liability for damages shall not exceed the purchase price of the products used.

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